

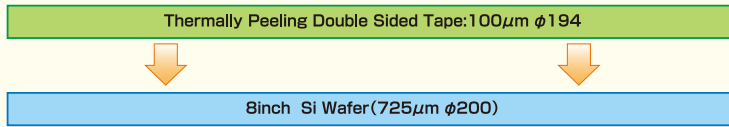
# ウエハーレベルパッケージ

## Wafer Level Packaging

1

### 熱剥離性両面テープをキャリアに貼り付け

Put a Thermally Peeling Double Sided Tape onto a Carrier Wafer

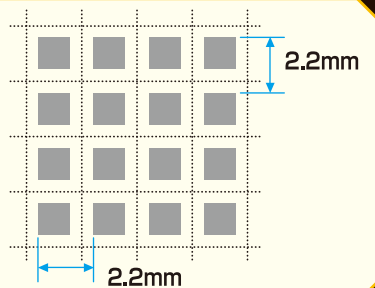
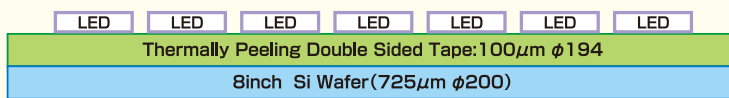


- 剥離温度170℃以上のものを選択
- Recomending Peeling Temperature is over 170℃

2

### チップをテープ上に搭載

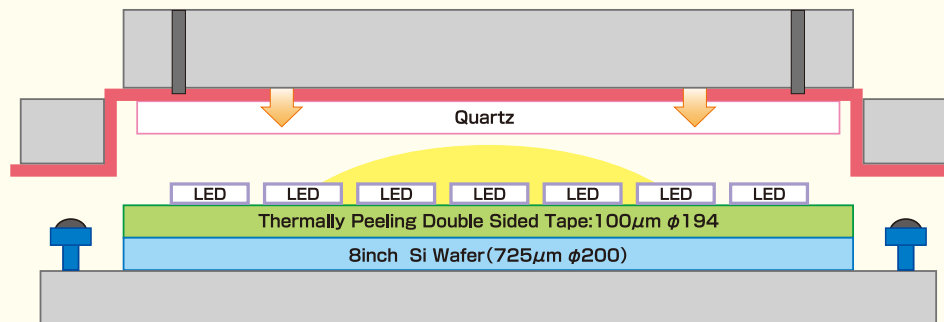
Chip mounting onto the tape



3

### コンプレッション成型

Molding Process of Phosphor Blended Silicone Encapsulant



- 合成石英を金型に保持
- Set a Quartz Wafer on a surface of a mold
- 封止材:メチルレジン KER-2300 + 蛍光体
- High Hardness Silicone Encapsulant KER-2300+ Phosphor

4

### ポストキュア

Post Molding Cure

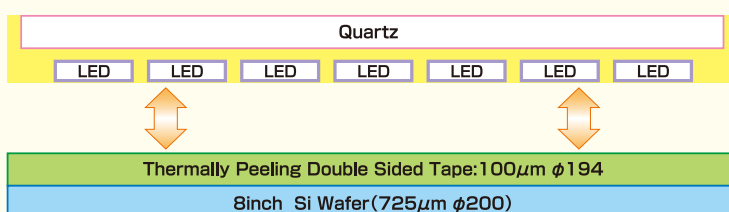


- 150℃×2時間
- 150℃ x 2h

5

### キャリア分離

Removing Molded Silicone from the Double Sided Tape



- 170℃加熱
- Heating over 170℃